

36903  
WHS

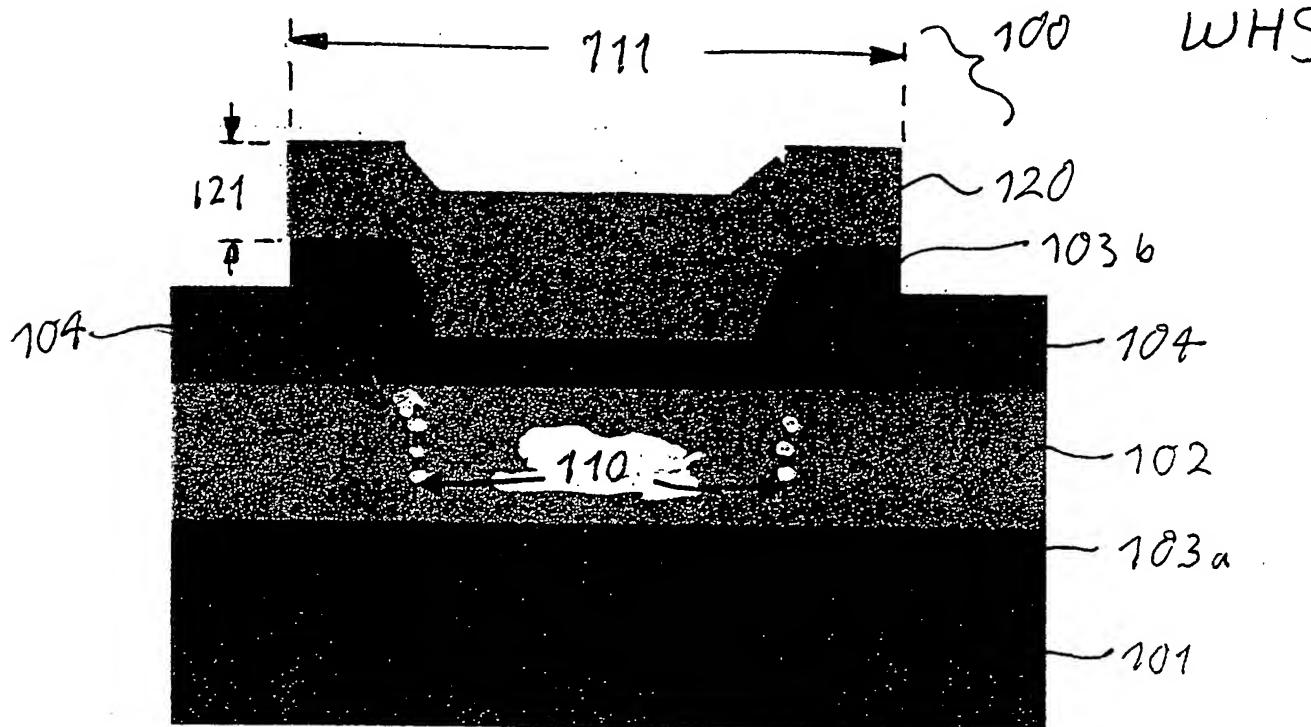
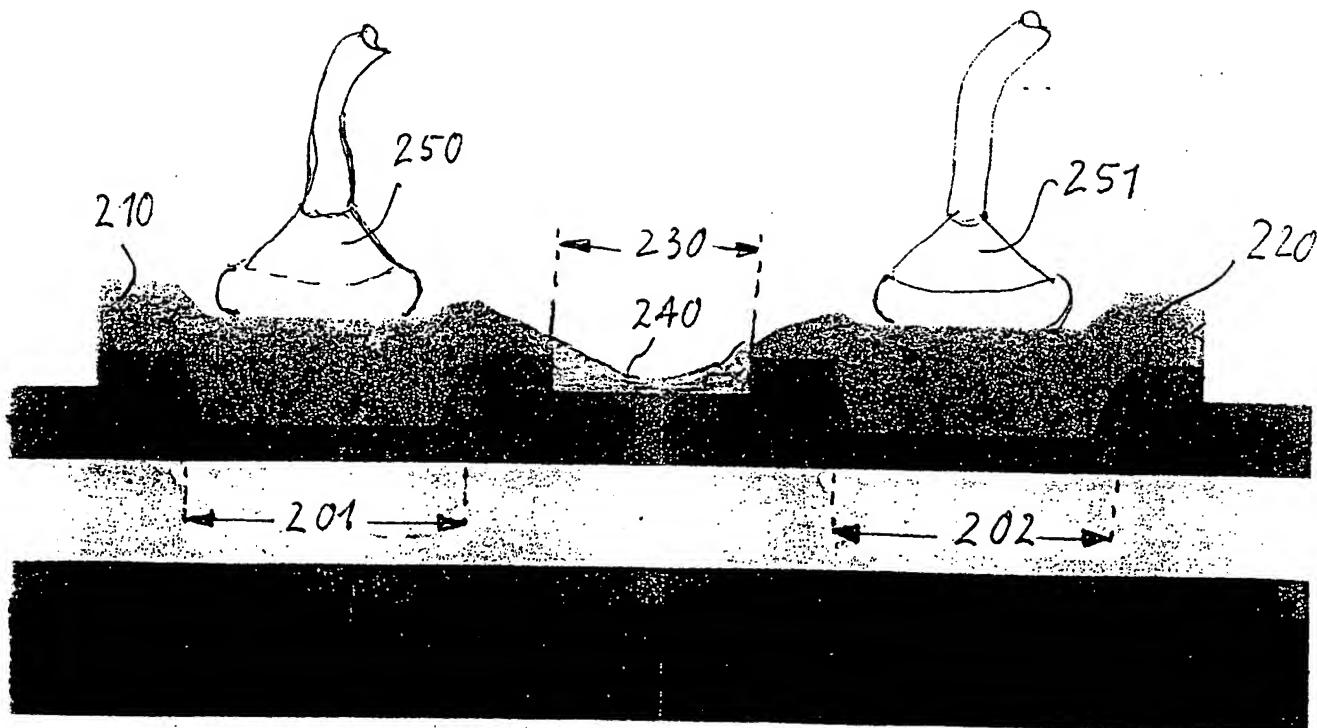


FIG. 1 (PRIOR ART)



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FIG. 2 (PRIOR ART)

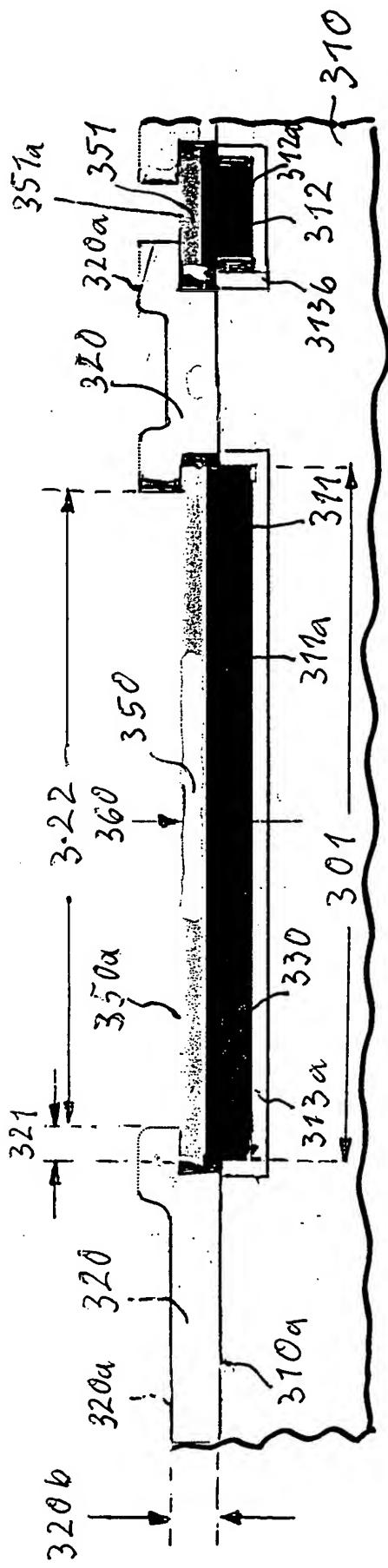


FIG. 3

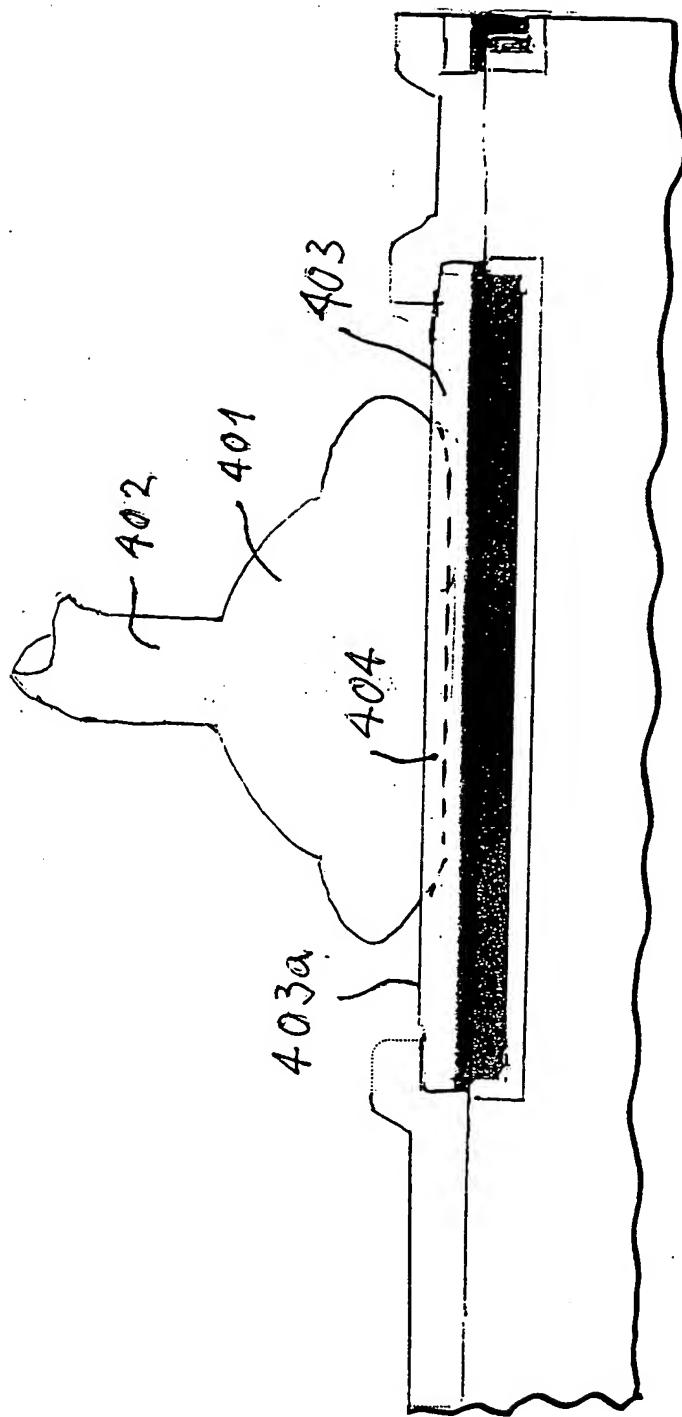


FIG. 4

501 — Start

- 502 — Chemically-mechanically polishing the wafer to expose the copper contact pad areas
- 503 — Depositing a layer of barrier metal over the wafer
- 504 — Depositing a bondable metal layer over the barrier metal layer
- 505 — Patterning both deposited metal layers, letting the portions over the contact pad areas remain
- 506 — Depositing a layer of protective overcoat over the wafer in a thickness so that the exposed overcoat surface lies at or above the exposed bondable metal surface
- 507 — Opening windows in the overcoat layer so that the bondable metal plugs are exposed
- 508 — Stop

FIG. 5